

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
Jun KISHIMOTO
Serial No: Not Assigned [parent 09/447,309]
Filed: November 14, 2001
For: SEMICONDUCTOR WAFER AND
METHOD FOR FABRICATION THEREOF

Art Unit: Not Assigned
Examiner: Not Assigned

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to examination of the above-identified Divisional Application, please amend the application as follows:

IN THE SPECIFICATION:

✓
Rewrite the paragraph which begins on line 22 of page 17 as follows:

B₁
(3) On the back surface, there remained grinding striations as micro roughness having a P-V value of about 30 to 50 nm and an interval of about 1 to 10 mm. However, they were very fine, and therefore, the grinding striations on the back surface were not transferred to the front surface of the wafer when the wafer was chucked during device process.

IN THE CLAIMS:

✓
Please add the following new claims:

B₂
--6. (New) A semiconductor wafer, wherein the wafer has opposite front and back surfaces, the front surface is subjected to a finishing mirror-polishing